



Material Content Data Sheet



Sales Product Name		TLE4275G		Issued		25. September 2017		
MA#		MA000714082						
Package		PG-TO263-5-1		Weight*		1674.16 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.794	0.23	0.23	2266	2266
leadframe	inorganic material	phosphorus	7723-14-0	0.145	0.01		87	
	non noble metal	iron	7439-89-6	0.483	0.03		288	
	non noble metal	copper	7440-50-8	482.096	28.80	28.84	287964	288339
	non noble metal	aluminium	7429-90-5	0.201	0.01	0.01	120	120
wire	non noble metal	aluminium	7429-90-5	0.201	0.01	0.01	120	120
encapsulation	organic material	carbon black	1333-86-4	1.455	0.09		869	
	plastics	epoxy resin	-	66.936	4.00		39982	
	inorganic material	silicondioxide	60676-86-0	659.177	39.35	43.44	393735	434586
leadfinish	non noble metal	tin	7440-31-5	12.370	0.74	0.74	7389	7389
plating	inorganic material	phosphorus	7723-14-0	0.001	0.00		1	
	non noble metal	nickel	7440-02-0	0.243	0.01	0.01	145	146
solder	non noble metal	tin	7440-31-5	0.105	0.01		62	
	noble metal	silver	7440-22-4	0.131	0.01		78	
	non noble metal	lead	7439-92-1	4.995	0.30	0.32	2983	3123
heatspreader	inorganic material	phosphorus	7723-14-0	0.133	0.01		79	
	non noble metal	iron	7439-89-6	0.442	0.03		264	
	non noble metal	copper	7440-50-8	441.456	26.37	26.41	263688	264031
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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